

## **CLAIM AMENDMENTS:**

Claim 1 (Cancel).

Claim 2 (Original): A semiconductor package comprising:

a tape carrier;

a first semiconductor element having a surface and a first electrode, on which surface the first electrode is provided;

a longer lead having two ends and a first land, the one end being connected to the first electrode and the other end forming the first land on the tape carrier;

a second semiconductor element having a surface and a second electrode, on which surface the second electrode is provided, and the first semiconductor element is stacked;

a shorter lead having two ends and a second land, the one end being connected to the second electrode and the other end forming a second land on the tape carrier;

a resin material which seals the first semiconductor element, the second semiconductor element, the longer lead and the shorter lead; and

solder balls, which are mounted on the first and second lands for external connection.

Claim 3 (Cancel).

Claim 4 (Original). A semiconductor package according to claim 2, further comprising at least another longer lead and at least another shorter lead, wherein each

of the longer leads and each of the shorter leads are arranged so as to alternate with each other.

Claim 5 (Cancel).

Claim 6 (Original): A semiconductor package according to claim 2, wherein the second semiconductor element is larger than the first semiconductor element, and comprises a surface area that faces the first semiconductor element and the second electrode is disposed outside said area.

Claim 7 (Cancel).

Claim 8 (Original): A semiconductor package according to claim 2, wherein:

the first semiconductor element includes a first surface, on which the first electrode is formed, and a second surface, which is opposite the first surface;

the second semiconductor element includes a third surface, on which the second electrode is formed, and a fourth surface, which is opposite the third surface; and

the first semiconductor element and the second semiconductor element are stacked such that the second surface faces the third surface.

Claim 9 (Cancel).

Claim 10 (Original): A semiconductor package according to claim 8, wherein the fourth surface is substantially devoid of the resin material, and the resin material is applied to substantially the remainder of the package.

Claim 11 (Cancel).

Claim 12 (Original): A semiconductor package according to claim 2, wherein each of the second semiconductor element and the first semiconductor element has two sets of substantially parallel edges, and each of the longer and the shorter leads extends substantially orthogonally to each edge.

Claim 13 (Cancel).

Claim 14 (Original): A semiconductor package according to claim 2, wherein the longer lead and the shorter lead extend outwardly in substantially the same plane.

Claim 15 (Cancel).

Claim 16 (Original): A semiconductor package according to claim 8, wherein the second surface is adhered to the third surface.

Claim 17-18 (Cancel).

Claim 19 (Currently Amended): A tape carrier ~~according to claim 18~~, comprising:  
a base tape having a device hole formed therein; and  
leads, which include inner lead portions, are provided on the base tape, wherein  
the inner lead portions, which extend from the periphery of the device hole  
toward the center of the device hole, have different lengths;  
wherein the inner lead portions are in sets of different lengths and disposed at  
substantially regular intervals; and  
wherein the inner lead portions include three different lengths.

Claim 20 (Original): A tape carrier package comprising:  
a base tape;  
a first semiconductor element having an upper surface and a first electrode, on  
which upper surface the first electrode is provided;  
a first lead, which first lead is provided on the base tape and connected to the  
first electrode;  
a second semiconductor element having an upper surface and a second  
electrode, on which upper surface the second electrode is provided,  
a second lead, which is shorter than the first lead, and is provided on the base  
tape and connected to the second electrode;  
a third semiconductor element having an upper surface and a third electrode, on  
which upper surface the third electrode is provided;  
a third lead, which is shorter than the second lead, provided on the base tape  
and connected to the third electrode; and

a molding member, which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, the first lead, the second lead and the third lead.

Claim 21 (Original): A tape carrier package according to claim 20, wherein the first and second semiconductor elements comprise a lower surface and the semiconductor elements are held such that a space is formed between the lower surface of the first semiconductor element and the upper surface of the second semiconductor element, and between the lower surface of the second semiconductor element and the upper surface of the third semiconductor element, and a mold is formed around the resulting structure.

Claim 22 (Original): A tape carrier package according to claim 20, wherein each of the first, second and third semiconductor elements has an upper and a lower surface, and the semiconductor elements are stacked such that the lower surface of the first semiconductor element and the upper surface of the second semiconductor element are adhered to each other, and the lower surface of the second semiconductor element and the upper surface of the third semiconductor element are adhered to each other.

Claim 23 (Original): A tape carrier package, comprising:  
a base tape;

a first semiconductor element having upper and lower surfaces and a first electrode, on which upper surface the first electrode is provided;

a first lead, which is provided on the base tape and connected to the first electrode;

a second semiconductor element having upper and lower surfaces and a second electrode, on which upper surface the second electrode is provided, the second semiconductor element being disposed such that the side surfaces of the first semiconductor element and the second semiconductor element are opposite each other, with a space formed therebetween;

a first lead which is provided on the base tape and connected to the second electrode;

a third semiconductor element having an upper surface and a third electrode, on which upper surface the third electrode is provided, and which is disposed at lower surface side of the first semiconductor element and the second semiconductor element;

a second lead which is shorter than the first lead, provided on the base tape and connected to the third electrode;

a molding member which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, and the first lead and the second lead, wherein

both the lower surface of the first semiconductor element and the lower surface of the second semiconductor element are adhered to the upper surface of the third semiconductor element.

Claim 24 (Original): A tape carrier package according to claim 21, wherein:  
a plurality of first electrodes and a plurality of second electrodes are provided;  
and  
some of the first electrodes and some of the second electrodes are connected to each other.

Claim 25 (Original): A tape carrier package comprising:  
a base tape;  
a first semiconductor element having an upper surface and a first electrode, on which upper surface the first electrode is provided;  
a first lead, which is provided on the base tape and connected to the first electrode;  
a second semiconductor element on which upper surface a second electrode is provided;  
a third semiconductor element having an upper surface and a third electrode, on which upper surface the third electrode is provided, the third semiconductor element being disposed such that the side surfaces of the second semiconductor element and the third semiconductor element are opposite each other and a space is formed therebetween;  
a second lead, which is shorter than the first lead, the second lead being provided on the base tape and connected to the second electrode and the third electrode; and

a molding member which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, the first lead and the second lead, wherein

the lower surface of the first semiconductor element is adhered to both the upper surface of the second semiconductor element and the upper surface of the third semiconductor element.

Claim 26 (Original): A tape carrier package comprising:

a base tape;

a first semiconductor element having a lower surface, on which lower surface a first electrode is provided;

a first lead, which is provided on the base tape and connected to the first electrode;

a second semiconductor element having an upper surface, on which upper surface a second electrode is provided;

a second lead, which is shorter than the first lead, and is provided on the base tape and connected to the second electrode; and

a molding member which seals the first semiconductor element, the second semiconductor element, and the first lead and the second lead, wherein

the second semiconductor element is held so as to be spaced apart from the lower surface side of the first semiconductor element.



Claim 27 (Original): A tape carrier comprising:

- a base tape having a device hole;
- lands, which are provided on the base tape and arranged in a grid pattern;
- a plurality of leads, each having an outer lead portion and an inner lead portion, which outer lead portions are connected to the plurality of lands;
- a solder resist provided on the lead which includes an opening through which the land is exposed; and
- a metal ball which is connected to the land via the opening, wherein the inner lead portions, which extend from the periphery of the device hole toward the center of the device hole, having several different lengths.

Claim 28 (Original): A tape carrier comprising:

- a base tape having a device hole formed therein and a lower surface;
- lands, provided on the base tape and arranged in a grid pattern;
- openings through which the lands are exposed to the lower surface side of the base tape;
- leads having outer leads and inner leads, the outer lead portions being connected to the plurality of lands;
- a solder resist provided on the leads; and
- a metal ball which is connected to the land via the opening, wherein inner lead portions of the leads which extend from the periphery of the device hole toward the center of the device hole have several different lengths.

Claim 29 (Original): A tape carrier according to claim 28, wherein the solder resist includes openings through which the upper surfaces of the lands are exposed.

Claim 30 (Original): A tape carrier according to claim 27, wherein the inner lead portions having different lengths are disposed regularly.

Claim 31 (Original): A tape carrier according to claim 28, wherein the inner lead portions are in sets of different lengths and are disposed at substantially regular intervals.

Claim 32 (Original): A semiconductor device in which a plurality of tape carriers according to claim 29 is stacked.

Claim 33 (New): A semiconductor package, comprising:

- a tape carrier;
- a first semiconductor element mounted on the tape carrier;
- a second semiconductor element mounted on the tape carrier;
- a short lead provided on the tape carrier, and being connected to the first semiconductor element; and
- a long lead provided on the tape carrier, and being connected to the second semiconductor element.

Claim 34 (New): A semiconductor package recited in claim 33, wherein the second semiconductor element is disposed on the first semiconductor element.

Claim 35 (New): A semiconductor package recited in claim 34, wherein the first semiconductor element has a surface and a first electrode, on which surface the first electrode is provided;

wherein the long lead has two ends and a first land, the one end being connected to the first electrode and the other end forming the first land on the tape carrier;

wherein the second semiconductor element has a surface and a second electrode, on which surface the second electrode is provided, and the first semiconductor element is stacked; and

wherein the short lead has two ends and a second land, the one end being connected to the second electrode and the other end forming a second land on the tape carrier;

and wherein the semiconductor package further comprises a resin material which seals the first semiconductor element, the second semiconductor element, the longer lead and the shorter lead; and

solder balls, which are mounted on the first and second lands for external connection

Claim 36 (New): A semiconductor package according to claim 35, further comprising at least another longer lead and at least another shorter lead, wherein each

of the longer leads and each of the shorter leads are arranged so as to alternate with each other.

Claim 37 (New): A semiconductor package according to claim 35, wherein the second semiconductor element is larger than the first semiconductor element, and comprises a surface area that faces the first semiconductor element and the second electrode is disposed outside said area.

Claim 38 (New): A semiconductor package according to claim 35, wherein:  
the first semiconductor element includes a first surface, on which the first electrode is formed, and a second surface, which is opposite the first surface;  
the second semiconductor element includes a third surface, on which the second electrode is formed, and a fourth surface, which is opposite the third surface; and  
the first semiconductor element and the second semiconductor element are stacked such that the second surface faces the third surface.

Claim 39 (New): A semiconductor package according to claim 38, wherein the fourth surface is substantially devoid of the resin material, and the resin material is applied to substantially the remainder of the package.

Claim 40 (New): A semiconductor package according to claim 35, wherein each of the second semiconductor element and the first semiconductor element has two sets

of substantially parallel edges, and each of the longer and the shorter leads extends substantially orthogonally to each edge.

Claim 41 (New): A semiconductor package according to claim 35, wherein the longer lead and the shorter lead extend outwardly in substantially the same plane.

Claim 42 (New): A semiconductor package according to claim 38, wherein the second surface is adhered to the third surface.

Claim 43 (New): A semiconductor package according to claim 34, wherein:

- the first semiconductor element has an upper surface and a first electrode, on which upper surface the first electrode is provided;
- the short lead is connected to the first electrode;
- the second semiconductor element has an upper surface and a second electrode, on which upper surface the second electrode is provided; and
- the long lead is connected to the second electrode;

said semiconductor package further comprising:

- a third semiconductor element having an upper surface and a third electrode, on which upper surface the third electrode is provided;
- a further lead, which is shorter than the short lead, provided on the tape carrier and being connected to the third electrode; and

a molding member, which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, the first lead, the second lead and the third lead.

Claim 44 (New): A semiconductor package according to claim 34,  
wherein the first semiconductor element has an upper surface and a first electrode, on which upper surface the first electrode is provided;  
wherein the short lead is connected to the first electrode; and  
wherein the second semiconductor element has an upper surface and a second electrode, on which upper surface the second electrode is provided;  
the semiconductor package further comprising a third semiconductor element having an upper surface and a third electrode, on which upper surface the third electrode is provided, the third semiconductor element being disposed such that side surfaces of the first semiconductor element and the third semiconductor element are opposite each other and a space is formed therebetween;  
a further short lead provided on the tape carrier and being connected to the third electrode; and  
a molding member which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, the long lead and the short leads, wherein  
the lower surface of the second semiconductor element is adhered to both the upper surface of the first semiconductor element and the upper surface of the third semiconductor element.

Claim 45 (New): A semiconductor package according to claim 34,  
wherein the tape carrier has a device hole, and lands which are arranged in a  
grid pattern;  
wherein each lead has an outer lead portion and an inner lead portion, which  
outer lead portions are connected to the plurality of lands;  
wherein a solder resist is provided on the lead which includes an opening  
through which the land is exposed;  
wherein a metal ball is connected to the land via the opening; and  
wherein the inner lead portions, which extend from a periphery of the device hole  
toward a center of the device hole, have several different lengths.

Claim 46 (New): A semiconductor package according to claim 45, wherein the  
inner lead portions having different lengths are disposed regularly.

Claim 47 (New): A semiconductor package as recited in claim 34, wherein the  
tape carrier has a device hole formed therein, a lower surface, and lands arranged in a  
grid pattern;

wherein openings are formed through which the lands are exposed to the lower  
surface side of the base tape;

wherein the leads have outer lead portions and inner lead portions, the outer  
lead portions being connected to the plurality of lands;

wherein a solder resist is provided on the leads;

wherein a metal ball is connected to the land via the opening; and

wherein the inner lead portions of the leads extend from a periphery of the device hole toward a center of the device hole and have several different lengths.

Claim 48 (New): A semiconductor package according to claim 47, wherein the solder resist includes openings through which the upper surfaces of the lands are exposed.

Claim 49 (New): A semiconductor package according to claim 47, wherein the inner lead portions are in sets of different lengths and are disposed at substantially regular intervals.

Claim 50 (New): A semiconductor package according to claim 34, wherein the first semiconductor element has upper and lower surfaces and a first electrode, on which upper surface the first electrode is provided;

wherein the short lead is connected to the first electrode;

wherein the second semiconductor element has upper and lower surfaces and a second electrode, on which upper surface the second electrode is provided; and

wherein the long lead is connected to the second electrode;

the semiconductor package further comprising a third semiconductor element having an upper surface and a third electrode, on which upper surface the third electrode is provided, the second semiconductor element being disposed such that side surfaces of the second semiconductor element and the third semiconductor element



are opposite each other, with a space formed therebetween, the second semiconductor element and the third semiconductor element being adhered to the upper surface of the first semiconductor element;

a further long lead which is connected to the third electrode; and

a molding member which seals the first semiconductor element, the second semiconductor element, the third semiconductor element, and the long leads and the short lead.

Claim 51 (New): A semiconductor package recited in claim 33, wherein the tape carrier is sandwiched between the second semiconductor element and the first semiconductor element.

Claim 52 (New): A semiconductor package recited in claim 51, wherein the first semiconductor element has a lower surface, on which lower surface a first electrode is provided;

wherein the short lead is connected to the first electrode;

wherein the second semiconductor element has an upper surface, on which upper surface a second electrode is provided;

wherein the long lead is connected to the second electrode;

wherein a molding member seals the first semiconductor element, the second semiconductor element, and the long lead and the short lead; and

wherein the first semiconductor element is held so as to be spaced apart from the second semiconductor element.